ADC0801/ADC0802/ADC0803/ADC0804/ADC0805
8-Bit µP Compatible A/D Converters

General Description
The ADC0801, ADC0802, ADC0803, ADC0804 and ADC0805 are CMOS 8-bit successive approximation A/D converters that use a differential potentiometric ladder—similar to the 256R products. These converters are designed to allow operation with the NSC800 and INS8080A derivative control bus with TRI-STATE® output latches directly driving the data bus. These A/Ds appear like memory locations or I/O ports to the microprocessor and no interfacing logic is needed.

Differential analog voltage inputs allow increasing the common-mode rejection and offsetting the analog zero input voltage value. In addition, the voltage reference input can be adjusted to allow encoding any smaller analog voltage span to the full 8 bits of resolution.

Features
- Compatible with 8080 µP derivatives—no interfacing logic needed - access time - 135 ns
- Easy interface to all microprocessors, or operates "stand alone"
- Differential analog voltage inputs
- Logic inputs and outputs meet both MOS and TTL voltage level specifications
- Works with 2.5V (LM336) voltage reference
- On-chip clock generator
- 0V to 5V analog input voltage range with single 5V supply
- No zero adjust required
- 0.3" standard width 20-pin DIP package
- 20-pin molded chip carrier or small outline package
- Operates ratiometrically or with 5 VDC, 2.5 VDC, or analog span adjusted voltage reference

Key Specifications
- Resolution 8 bits
- Total error ±1/3 LSB, ±1/5 LSB and ±1 LSB
- Conversion time 100 µs

Typical Applications

Error Specification (Includes Full-Scale, Zero Error, and Non-Linearity)

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Full-Scale Adjusted</th>
<th>VREF/2 – 2.500 VDC (No Adjustments)</th>
<th>VREF/2 – No Connection (No Adjustments)</th>
</tr>
</thead>
<tbody>
<tr>
<td>ADC0801</td>
<td>±1/3 LSB</td>
<td></td>
<td></td>
</tr>
<tr>
<td>ADC0802</td>
<td>±1/5 LSB</td>
<td></td>
<td></td>
</tr>
<tr>
<td>ADC0803</td>
<td>±1/5 LSB</td>
<td></td>
<td></td>
</tr>
<tr>
<td>ADC0804</td>
<td>±1 LSB</td>
<td></td>
<td></td>
</tr>
<tr>
<td>ADC0805</td>
<td>±1 LSB</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>
Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

Supply Voltage (\(V_{CC}\)) (Note 3) 6.5V

Voltage

Logic Control Inputs

\[-0.3V\text{ to } +18V\]

At Other Input and Outputs

\[-0.3V\text{ to } (V_{CC} + 0.3V)\]

Lead Temp. (Soldering, 10 seconds)

Dual-In-Line Package (plastic) 260°C

Dual-In-Line Package (ceramic) 300°C

Surface Mount Package

Vapor Phase (60 seconds) 215°C

Infrared (15 seconds) 220°C

Storage Temperature Range

\[-65°C \text{ to } +150°C\]

Package Dissipation at \(T_A = 25°C\) 875 mW

ESD Susceptibility (Note 10) 800V


g Operating Ratings (Notes 1 & 2)

Temperature Range

\(T_{MIN} \leq T_A \leq T_{MAX}\)

ADC0801/02/02LJ, ADC0802LJ/883

\[-55°C \leq T_A \leq +125°C\]

ADC0801/02/03/04LCN

\[-40°C \leq T_A \leq +85°C\]

ADC0801/02/03/05LCN

\[-40°C \leq T_A \leq +85°C\]

ADC0802LCN

\[0°C \leq T_A \leq +70°C\]

ADC0802/03/04LCV

\[0°C \leq T_A \leq +70°C\]

ADC0802/03/04LCWM

Range of \(V_{CC}\)

4.5 \(V_{DC}\) to 6.3 \(V_{DC}\)

Electrical Characteristics

The following specifications apply for \(V_{CC} = 5 \ V_{DC}\), \(T_{MIN} \leq T_A \leq T_{MAX}\) and \(f_{CLK} = 640 \ kHz\) unless otherwise specified.

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>ADC0801: Total Adjusted Error (Note 8)</td>
<td>With Full-Scale Adj. (See Section 2.5.2)</td>
<td>±1/4</td>
<td>LSB</td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>ADC0802: Total Unadjusted Error (Note 8)</td>
<td>(V_{REF}/2) = 2.500 (V_{DC})</td>
<td>±1/8</td>
<td>LSB</td>
<td></td>
</tr>
<tr>
<td></td>
<td>ADC0803: Total Adjusted Error (Note 8)</td>
<td>With Full-Scale Adj. (See Section 2.5.2)</td>
<td>±1/8</td>
<td>LSB</td>
<td></td>
</tr>
<tr>
<td></td>
<td>ADC0804: Total Unadjusted Error (Note 8)</td>
<td>(V_{REF}/2) = 2.500 (V_{DC})</td>
<td>±1</td>
<td>LSB</td>
<td></td>
</tr>
<tr>
<td></td>
<td>ADC0805: Total Unadjusted Error (Note 8)</td>
<td>(V_{REF}/2)-No Connection</td>
<td>±1</td>
<td>LSB</td>
<td></td>
</tr>
<tr>
<td>VREF/2 Input Resistance (Pin 9)</td>
<td>ADC0801/02/03/05</td>
<td>2.5</td>
<td>8.0</td>
<td>(V_{DC})</td>
<td>k(\Omega)</td>
</tr>
<tr>
<td></td>
<td>ADC0804 (Note 9)</td>
<td>0.75</td>
<td>1.1</td>
<td>(V_{DC})</td>
<td>k(\Omega)</td>
</tr>
<tr>
<td>Analog Common-Mode Error</td>
<td>Over Analog Input Voltage Range</td>
<td>±1/16</td>
<td>±1/4</td>
<td>LSB</td>
<td></td>
</tr>
</tbody>
</table>
| Power Supply Sensitivity                               | \(V_{CC} - 5 \ V_{DC} \leq 10\%\) Over Allowed \(V_{IN}(+)\) and \(V_{IN}(-)\) 
Voltage Range (Note 4)                                  | ±1/16                                           | ±1/4   | LSB    |

AC Electrical Characteristics

The following specifications apply for \(V_{CC} = 5 \ V_{DC}\) and \(T_A = 25°C\) unless otherwise specified.

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>(T_C)</td>
<td>Conversion Time</td>
<td>(f_{CLK} = 640 \ kHz) (Note 6)</td>
<td>103</td>
<td>114</td>
<td>(\mu)s</td>
<td></td>
</tr>
<tr>
<td>(T_{CC})</td>
<td>Conversion Time</td>
<td>(Note 5, 6)</td>
<td>66</td>
<td>73</td>
<td>(1/f_{CLK})</td>
<td></td>
</tr>
<tr>
<td>(f_{CLK})</td>
<td>Clock Frequency</td>
<td>(V_{CC} = 5 \ V_{DC}) (Note 5)</td>
<td>100</td>
<td>640</td>
<td>1460 kHz</td>
<td></td>
</tr>
<tr>
<td>CR</td>
<td>Conversion Rate in Free-Running Mode</td>
<td>(\text{INTR} \text{ tied to } \text{WR} \text{ with } CS = 0 \text{ (V_{DC})})</td>
<td>8770</td>
<td>9708</td>
<td>\text{conv/s}</td>
<td></td>
</tr>
<tr>
<td>(I_{W(0)})</td>
<td>Width of \text{WR} Input (Start Pulse Width)</td>
<td>(CS = 0 \text{ (V_{DC})}) (Note 7)</td>
<td>100</td>
<td>ns</td>
<td></td>
<td></td>
</tr>
<tr>
<td>(I_{ACC})</td>
<td>Access Time (Delay from Falling Edge of \text{RD} to Output Data Valid)</td>
<td>(C_L = 100 \text{ pF})</td>
<td>135</td>
<td>200</td>
<td>ns</td>
<td></td>
</tr>
<tr>
<td>(I_{IH}, I_{OH})</td>
<td>TRI-STATE Control (Delay from Rising Edge of \text{RD} to Hi-Z State)</td>
<td>(C_L = 10 \text{ pF}, R_L = 10k) (See TRI-STATE Test Circuits)</td>
<td>125</td>
<td>200</td>
<td>ns</td>
<td></td>
</tr>
<tr>
<td>(I_{IHI}, I_{IHI})</td>
<td>Delay from Falling Edge of \text{WR} or \text{RD} to Reset of \text{INTR}</td>
<td></td>
<td>300</td>
<td>450</td>
<td>ns</td>
<td></td>
</tr>
<tr>
<td>(C_{IN})</td>
<td>Input Capacitance of Logic Control Inputs</td>
<td>5</td>
<td>7.5</td>
<td>pF</td>
<td></td>
<td></td>
</tr>
<tr>
<td>(C_{OUT})</td>
<td>TRI-STATE Output Capacitance (Data Buffers)</td>
<td>5</td>
<td>7.5</td>
<td>pF</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

CONTROL INPUTS [Note: CLK IN (Pin 4) is the input of a Schmitt trigger circuit and is therefore specified separately]

\(V_{IN}(1)\) Logical "1" Input Voltage (Except Pin 4 CLK IN) \(V_{CC} \leq 5.25 \ V_{DC}\) \(2.0\) \(15\) \(V_{DC}\)
### AC Electrical Characteristics (Continued)

The following specifications apply for \( V_{CC} = 5\,\text{VDC} \) and \( T_{\text{MIN}} \leq T_{A} \leq T_{\text{MAX}} \), unless otherwise specified.

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>( V_{IN} (0) )</td>
<td>Logical &quot;0&quot; Input Voltage (Except Pin 4 CLK IN)</td>
<td>( V_{CC} - 4.75,\text{VDC} )</td>
<td>0.8</td>
<td></td>
<td></td>
<td>( \text{VDC} )</td>
</tr>
<tr>
<td>( I_{IN} (1) )</td>
<td>Logical &quot;1&quot; Input Current (All Inputs)</td>
<td>( V_{IN} - 5,\text{VDC} )</td>
<td>0.005</td>
<td>1</td>
<td></td>
<td>( \mu\text{ADC} )</td>
</tr>
<tr>
<td>( I_{IN} (0) )</td>
<td>Logical &quot;0&quot; Input Current (All Inputs)</td>
<td>( V_{IN} - 0,\text{VDC} )</td>
<td>-1</td>
<td>-0.005</td>
<td></td>
<td>( \mu\text{ADC} )</td>
</tr>
</tbody>
</table>

#### CLOCK IN AND CLOCK R

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>( V_{T}^{+} )</td>
<td>CLK IN (Pin 4) Positive Going Threshold Voltage</td>
<td></td>
<td>2.7</td>
<td>3.1</td>
<td>3.5</td>
<td>( \text{VDC} )</td>
</tr>
<tr>
<td>( V_{T}^{-} )</td>
<td>CLK IN (Pin 4) Negative Going Threshold Voltage</td>
<td></td>
<td>1.5</td>
<td>1.8</td>
<td>2.1</td>
<td>( \text{VDC} )</td>
</tr>
<tr>
<td>( V_{H} )</td>
<td>CLK IN (Pin 4) Hysteresis ((V_{T}^{+}) - (V_{T}^{-}))</td>
<td></td>
<td>0.6</td>
<td>1.3</td>
<td>2.0</td>
<td>( \text{VDC} )</td>
</tr>
<tr>
<td>( V_{OUT} (0) )</td>
<td>Logical &quot;0&quot; CLK R Output Voltage</td>
<td>( I_{O} = -360,\mu\text{A} ), ( V_{CC} - 4.75,\text{VDC} )</td>
<td>0.4</td>
<td></td>
<td></td>
<td>( \text{VDC} )</td>
</tr>
<tr>
<td>( V_{OUT} (1) )</td>
<td>Logical &quot;1&quot; CLK R Output Voltage</td>
<td>( I_{O} = -960,\mu\text{A} ), ( V_{CC} - 4.75,\text{VDC} )</td>
<td>2.4</td>
<td></td>
<td></td>
<td>( \text{VDC} )</td>
</tr>
</tbody>
</table>

#### DATA OUTPUTS AND INTR

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>( V_{OUT} (0) )</td>
<td>Logical &quot;0&quot; Output Voltage Data Outputs</td>
<td>( I_{OUT} = 1.6,\text{mA} ), ( V_{CC} - 4.75,\text{VDC} )</td>
<td></td>
<td>0.4</td>
<td></td>
<td>( \text{VDC} )</td>
</tr>
<tr>
<td>( V_{OUT} (1) )</td>
<td>Logical &quot;1&quot; Output Voltage Data Outputs</td>
<td>( I_{OUT} = -0.6,\text{mA} ), ( V_{CC} - 4.75,\text{VDC} )</td>
<td></td>
<td></td>
<td></td>
<td>( \text{VDC} )</td>
</tr>
<tr>
<td>( I_{OUT} )</td>
<td>TRI-STATE Disabled Output Leakage (All Data Buffers)</td>
<td>( V_{OUT} = 0,\text{VDC} ), ( V_{OUT} = 5,\text{VDC} )</td>
<td>-3</td>
<td>3</td>
<td></td>
<td>( \mu\text{ADC} )</td>
</tr>
<tr>
<td>( IS_{SOURCE} )</td>
<td>VOUT Short to Gnd, ( T_{A} = 25^\circ\text{C} )</td>
<td></td>
<td>4.5</td>
<td>6</td>
<td></td>
<td>( \mu\text{ADC} )</td>
</tr>
<tr>
<td>( IS_{INK} )</td>
<td>VOUT Short to VCC, ( T_{A} = 25^\circ\text{C} )</td>
<td></td>
<td>9.0</td>
<td>16</td>
<td></td>
<td>( \mu\text{ADC} )</td>
</tr>
</tbody>
</table>

#### POWER SUPPLY

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>( ICC )</td>
<td>Supply Current (Includes Ladder Current)</td>
<td>( f_{CLK} = 640,\text{kHz} ), ( V_{REF}/2 = \text{NC} ), ( T_{A} = 25^\circ\text{C} ) and ( \text{CS} = 5,\text{V} )</td>
<td></td>
<td>1.1</td>
<td>1.8</td>
<td></td>
</tr>
<tr>
<td>ADC0801/02/03/04LCJ/05</td>
<td></td>
<td></td>
<td></td>
<td>1.9</td>
<td>2.5</td>
<td></td>
</tr>
<tr>
<td>ADC0804LCJ/04LCWM</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

---

**Note 1:** Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its specified operating conditions.

**Note 2:** All voltages are measured with respect to Gnd, unless otherwise specified. The separate A Gnd point should always be wired to the D Gnd.

**Note 3:** A zener diode exists, internally, from \( V_{CC} \) to Gnd and has a typical breakdown voltage of 7 \( \text{VDC} \).

**Note 4:** For \( V_{IN} = 5\,\text{VDC} \) the digital output code will be 0000 0000. Two on-chip diodes are tied to each analog input (see block diagram) which will forward conduct for analog input voltages one diode drop below ground or one diode drop greater than the \( V_{CC} \) supply. Be careful, during testing at low \( V_{CC} \) levels (4.5\,\text{V}), as high level analog inputs (5\,\text{V}) can cause this input diode to conduct—especially at elevated temperatures, and cause errors for analog inputs near full-scale. The spec allows 50 mV forward bias of either diode. This means that as long as the analog \( V_{IN} \) does not exceed the supply voltage by more than 50 mV, the output code will be correct. To achieve an absolute 0 \( \text{VDC} \) to 5 \( \text{VDC} \) input voltage range will therefore require a minimum supply voltage of 4.950 \( \text{VDC} \) over temperature variations, initial tolerance and loading.

**Note 5:** Accuracy is guaranteed at \( f_{CLK} = 640\,\text{kHz} \). At higher clock frequencies accuracy can degrade. For lower clock frequencies, the duty cycle limits can be extended so long as the minimum clock high time interval or minimum clock low time interval is no less than 275 ns.

**Note 6:** With an asynchronous start pulse, up to 8 clock periods may be required before the internal clock phases are proper to start the conversion process. The start request is internally latched, see Figure 2 and section 2.0.

**Note 7:** The \( \text{CS} \) input is assumed to bracket the \( \text{WR} \) strobe input and therefore timing is dependent on the \( \text{WR} \) pulse width. An arbitrarily wide pulse width will hold the converter in a reset mode and the start of conversion is initiated by the low to high transition of the \( \text{WR} \) pulse (see timing diagrams).

**Note 8:** None of these A/Ds requires a zero adjust (see section 2.5.1). To obtain zero code at other analog input voltages see section 2.5 and Figure 5.

**Note 9:** The \( V_{REF}/2 \) pin is the center point of a two-resistor divider connected from \( V_{CC} \) to ground. In all versions of the ADC0801, ADC0802, ADC0803, and ADC0805, and in the ADC0804 LCJ, each resistor is typically 16 k\( \Omega \). In all versions of the ADC0804 except the ADC0804 LCJ, each resistor is typically 2.2 k\( \Omega \).

**Note 10:** Human body model, 100 pF discharged through a 1.5 k\( \Omega \) resistor.
Typical Performance Characteristics

- **Logic Input Threshold Voltage** vs. Supply Voltage
- **Delay From Falling Edge of RD to Output Data Valid** vs. Load Capacitance
- **CLK IN Schmitt Trip Levels** vs. Supply Voltage
- **fCLK vs. Clock Capacitor**
- **Full-Scale Error vs Conversion Time**
- **Effect of Unadjusted Offset Error vs VREF/2 Voltage**
- **Output Current vs Temperature**
- **Power Supply Current vs Temperature (Note 9)**
- **Linearity Error at Low VREF/2 Voltages**

TL/H/5671-2
TRI-STATE Test Circuits and Waveforms

Timing Diagrams (All timing is measured from the 50% voltage points)

Output Enable and Reset INTR

Note: Read strobe must occur 8 clock periods (8/CLK) after assertion of interrupt to guarantee reset of INTR.
Typical Applications (Continued)

6800 Interface

Ratiometric with Full-Scale Adjust

Note: before using caps at \( V_{IN} \) or \( V_{REF}/2 \), see section 2.3.2 Input Bypass Capacitors.

Absolute with a 2.500V Reference

Absolute with a 5V Reference

*For low power, see also LM385-2.5

Zero-Shift and Span Adjust: \( 2V \leq V_{IN} \leq 5V \)

Span Adjust: \( 0V \leq V_{IN} \leq 3V \)
Typical Applications (Continued)

Directly Converting a Low-Level Signal

A µP Interfaced Comparator

1 mV Resolution with µP Controlled Range

Digitizing a Current Flow
**Typical Applications (Continued)**

**Self-Clocking Multiple A/Ds**

*Use a large R value to reduce loading at CLK R output.*

**External Clocking**

- **fCLK**
  - 100 kHz ≤ fCLK ≤ 1460 kHz

**External Clocking**

- **VCLK**
  - 2.7 V max
  - 1.5 V max

**Self-Clocking in Free-Running Mode**

*After power-up, a momentary grounding of the WR input is needed to guarantee operation.*

**μP Interface for Free-Running A/D**

- **vREF**
  - Prevented from going A/D DATA UPDATE
  - (3 x VCC)

**Operating with "Automotive" Ratiometric Transducers**

*VXDR (~) = 0.15 VCC
15% of VCC = VXDR = 85% of VCC

**Ratiometric with VREF/2 Forced**

*TLVH/5671-7*
**Typical Applications** (Continued)

### \( \mu \)P Compatible Differential-Input Comparator with Pre-Set \( V_{OS} \) (with or without Hysteresis)

*See Figure 5 to select R value

\[ DB7 = \text{"1"} \text{ for } V \text{OUT}(+) > V \text{OUT}(-) + \left( V_{REF}/2 \right) \]

Omit circuitry within the dotted area if hysteresis is not needed

### Handling \( \pm 10V \) Analog Inputs

### Low-Cost, \( \mu \)P Interfaced, Temperature-to-Digital Converter

*Beckman Instruments #694-3-R10K resistor array

### \( \mu \)P Interfaced Temperature-to-Digital Converter

*Circuit values shown are for \( 0^\circ \text{C} < T_a < +128^\circ \text{C} \)

**Can calibrate each sensor to allow easy replacement, then A/D can be calibrated with a pre-set input voltage.
Typical Applications (Continued)

Handling ±5V Analog Inputs

μP Interfaced Comparator with Hysteresis

Analog Self-Test for a System

Read-Only Interface

Protecting the Input

A Low-Cost, 3-Decade Logarithmic Converter

*Beckman Instruments 694-3-R10K resistor array

Diodes are 1N914

*LM389 transistors

A, B, C, D = LM324A quad op amp
Typical Applications (Continued)

3-Decade Logarithmic A/D Converter

- Uses Chebyshev implementation for steeper roll-off
- Unity-gain, 2nd order, low-pass filter
- Adding a separate filter for each channel increases system response time if an analog multiplexer is used

Noise Filtering the Analog Input

Multiplexing Differential Inputs

Output Buffers with A/D Data Enabled

Increasing Bus Drive and/or Reducing Time on Bus

* A/D output data is updated 1 CLK period prior to assertion of

* Allows output data to set-up at falling edge of

TL/H/5671–10
Typical Applications (Continued)

Sampling an AC Input Signal

Note 1: Oversample whenever possible (keep fs > 2f<sub>b</sub> − 60) to eliminate input frequency folding (aliasing) and to allow for the skirt response of the filter.

Note 2: Consider the amplitude errors which are introduced within the passband of the filter.

70% Power Savings by Clock Gating

(Complete shutdown takes ≈ 30 seconds.)

Power Savings by A/D and V<sub>REF</sub> Shutdown

*Use ADC0801, 02, 03 or 05 for lowest power consumption.
Note: Logic inputs can be driven to V<sub>CC</sub> with A/D supply at zero volts.
Buffer prevents data bus from overdriving output of A/D when in shutdown mode.
Functional Description

1.0 UNDERSTANDING A/D ERROR SPECS

A perfect A/D transfer characteristic (staircase waveform) is shown in Figure 1a. The horizontal scale is analog input voltage and the particular points labeled are in steps of 1 LSB (19.53 mV with 2.5V tied to the VREF/2 pin). The digital output codes that correspond to these inputs are shown as D−1, D, and D+1. For the perfect A/D, not only will center-value (A−1, A, A+1, ...) analog inputs produce the correct output digital codes, but also each riser (the transitions between adjacent output codes) will be located ±1/2 LSB away from each center-value. As shown, the risers are ideal and have no width. Correct digital output codes will be provided for a range of analog input voltages that extend ±1/2 LSB from the ideal center-values. Each tread (the range of analog input voltage that provides the same digital output code) is therefore 1 LSB wide.

Figure 1b shows a worst case error plot for the ADC0801. All center-valued inputs are guaranteed to produce the correct output codes and the adjacent risers are guaranteed to be no closer to the center-value points than ±1/4 LSB. In other words, if we apply an analog input equal to the center-value ±1/4 LSB, we guarantee that the A/D will produce the correct digital code. The maximum range of the position of the code transition is indicated by the horizontal arrow and it is guaranteed to be no more than ±1/2 LSB. The error curve of Figure 1c shows a worst case error plot for the ADC0802. Here we guarantee that if we apply an analog input equal to the LSB analog voltage center-value the A/D will produce the correct digital code.

Next to each transfer function is shown the corresponding error plot. Many people may be more familiar with error plots than transfer functions. The analog input voltage to the A/D is provided by either a linear ramp or by the discrete output steps of a high resolution DAC. Notice that the error is continuously displayed and includes the quantization uncertainty of the A/D. For example the error at point 1 of Figure 1a is ±1/2 LSB because the digital code appeared 1/2 LSB in advance of the center-value of the tread. The error plots always have a constant negative slope and the abrupt upside steps are always 1 LSB in magnitude.

FIGURE 1. Clarifying the Error Specs of an A/D Converter
2.0 FUNCTIONAL DESCRIPTION

The ADC0801 series contains a circuit equivalent of the 256R network. Analog switches are sequenced by successive approximation logic to match the analog difference input voltage \( |V_{IN}(+)| - |V_{IN}(-)| \) to a corresponding tap on the R network. The most significant bit is tested first and after 8 comparisons (64 clock cycles) a digital 8-bit binary code (1111 1111 full-scale) is transferred to an output latch and then an interrupt is asserted (INTR makes a high-to-low transition). A conversion in process can be interrupted by issuing a second start command. The device may be operated in the free-running mode by connecting INTR to the CS input with WR 0. To ensure start-up under all possible conditions, an external WR pulse is required during the first power-up cycle.

On the high-to-low transition of the WR input the internal SAR latch and the shift register stages are reset. As long as the CS input and WR input remain low, the A/D will remain in a reset state. Conversion will start from 1 to 8 clock periods after at least one of these inputs makes a low-to-high transition.

A functional diagram of the A/D converter is shown in Figure 2. All of the package pinouts are shown and the major logic control paths are drawn in heavier weight lines. The converter is started by having CS and WR simultaneously low. This sets the start flip-flop (F/F) and the resulting “1” level resets the 8-bit shift register, resets the Interrupt (INTR) F/F and inputs a “1” to the D flop, F/F1, which is at the input end of the 8-bit shift register. Internal clock signals then transfer this “1” to the Q output of F/F1. The AN0 gate, G1, combines this “1” output with a clock signal to provide a reset signal to the start F/F. If the set signal is no longer present (either WR or CS is a “1”) the start F/F is reset and the 8-bit shift register then can have the “1” clocked in, which starts the conversion process. If the set signal were to still be present, this reset pulse would have no effect (both outputs of the start F/F would momentarily be at a “1” level) and the 8-bit shift register would continue to be held in the reset mode. This logic therefore allows for wide CS and WR inputs and the converter will start after at least one of these signals returns high and the internal clocks again provide a reset signal for the start F/F.

Note 1: CS shown twice for clarity.
Note 2: SAR = Successive Approximation Register.

FIGURE 2. Block Diagram
Functional Description (Continued)

After the “1” is clocked through the 8-bit shift register (which completes the SAR search) it appears as the input to the D-type latch, LATCH 1. As soon as this “1” is output from the shift register, the AND gate, G2, causes the new digital word to transfer to the TRI-STATE output latches. When LATCH 1 is subsequently enabled, the Q output makes a high-to-low transition which causes the INTR F/F to set. An inverting buffer then supplies the INTR input signal.

Note that this SET control of the INTR F/F remains low for 8 of the external clock periods (as the internal clocks run at 1/4 of the frequency of the external clock). If the data output is continuously enabled (CS and RD both held low), the INTR output will still signal the end of conversion (by a high-to-low transition), because the SET input can control the Q output of the INTR F/F even though the RESET input is constantly at a “1” level in this operating mode. This INTR output will therefore stay low for the duration of the SET signal, which is 8 periods of the external clock frequency (assuming the A/D is not started during this interval).

When operating in the free-running or continuous conversion mode (INTR pin tied to WR and CS wired low—see also section 2.8), the START F/F is SET by the high-to-low transition of the INTR signal. This resets the SHIFT REGISTER which causes the input to the D-type latch, LATCH 1, to go low. As the latch enable input is still present, the Q output will go high, which then allows the INTR F/F to be RESET. This reduces the width of the resulting INTR output pulse to only a few propagation delays (approximately 300 ns).

When data is to be read, the combination of both CS and RD being low will cause the INTR F/F to be reset and the TRI-STATE output latches will be enabled to provide the 8-bit digital outputs.

2.1 Digital Control Inputs

The digital control inputs (CS, RD, and WR) meet standard T2L logic voltage levels. These signals have been renamed when compared to the standard A/D Start and Output Enable labels. In addition, these inputs are active low to allow an easy interface to microprocessor control busses. For non-microprocessor based applications, the CS input (pin 1) can be grounded and the standard A/D Start function is obtained by an active low pulse applied at the WR input (pin 3) and the Output Enable function is caused by an active low pulse at the RD input (pin 2).

2.2 Analog Inputs

2.2.1 Input Current

Normal Mode

Due to the internal switching action, displacement currents will flow at the analog inputs. This is due to on-chip stray capacitance to ground as shown in Figure 3.

\[
\Delta V_e(\text{MAX}) = (V_p) \left( \frac{4.5}{2f_{cm}} \right) \text{ fCLK}
\]

\[
V_p = \frac{\Delta V_e(\text{MAX})}{(2f_{cm}) (4.5)}
\]

or

\[
V_p = \frac{(6 \times 10^{-3})(640 \times 10^3)}{(6.28)(60)(4.5)}
\]

which gives

\[
V_p \approx 1.9\text{V}
\]

The allowed range of analog input voltages usually places more severe restrictions on input common-mode noise levels.

An analog input voltage with a reduced span and a relatively large zero offset can be handled easily by making use of the differential input (see section 2.4 Reference Voltage).

2.3 Analog Inputs

2.3.1 Input Current

Normal Mode

Due to the internal switching action, displacement currents will flow at the analog inputs. This is due to on-chip stray capacitance to ground as shown in Figure 3.

\[
\Delta V_e(\text{MAX}) = (V_p) \left( \frac{4.5}{2f_{cm}} \right) \text{ fCLK}
\]

where:

\[
\Delta V_e
\]

is the error voltage due to sampling delay

\[
V_p
\]

is the peak value of the common-mode voltage

\[
f_{cm}
\]

is the common-mode frequency

As an example, to keep this error to 1/4 LSB (~ 5 mV) when operating with a 60 Hz common-mode frequency, \( f_{cm} \), and using a 640 kHz A/D clock, \( f_{CLK} \), would allow a peak value of the common-mode voltage, \( V_p \), which is given by:

\[
V_p = \left( \frac{\Delta V_e(\text{MAX})}{(2f_{cm}) (4.5)} \right)
\]

or

\[
V_p = \frac{(6 \times 10^{-3})(640 \times 10^3)}{(6.28)(60)(4.5)}
\]

which gives

\[
V_p \approx 1.9\text{V}
\]

The allowed range of analog input voltages usually places more severe restrictions on input common-mode noise levels.

An analog input voltage with a reduced span and a relatively large zero offset can be handled easily by making use of the differential input (see section 2.4 Reference Voltage).

2.4 Reference Voltage

This A/D has additional applications flexibility due to the analog differential voltage input. The \( V_{IN}(+\text{)} \) input (pin 7) can be used to automatically subtract a fixed voltage value from the input reading (tare correction). This is also useful in 4 mA–20 mA current loop conversion. In addition, common-mode noise can be reduced by use of the differential input. The time interval between sampling \( V_{IN}(+) \) and \( V_{IN}(-) \) is 4-1/4 clock periods. The maximum error voltage due to this slight time difference between the input voltage samples is given by:

\[
\Delta V_e(\text{MAX}) = (V_p) \left( \frac{4.5}{2f_{cm}} \right) \text{ fCLK}
\]

where:

\[
\Delta V_e
\]

is the error voltage due to sampling delay

\[
V_p
\]

is the peak value of the common-mode voltage

\[
f_{cm}
\]

is the common-mode frequency

As an example, to keep this error to 1/4 LSB (~ 5 mV) when operating with a 60 Hz common-mode frequency, \( f_{cm} \), and using a 640 kHz A/D clock, \( f_{CLK} \), would allow a peak value of the common-mode voltage, \( V_p \), which is given by:

\[
V_p = \left( \frac{\Delta V_e(\text{MAX})}{(2f_{cm}) (4.5)} \right)
\]

or

\[
V_p = \frac{(6 \times 10^{-3})(640 \times 10^3)}{(6.28)(60)(4.5)}
\]

which gives

\[
V_p \approx 1.9\text{V}
\]

The allowed range of analog input voltages usually places more severe restrictions on input common-mode noise levels.

An analog input voltage with a reduced span and a relatively large zero offset can be handled easily by making use of the differential input (see section 2.4 Reference Voltage).

2.3 Analog Inputs

2.3.1 Input Current

Normal Mode

Due to the internal switching action, displacement currents will flow at the analog inputs. This is due to on-chip stray capacitance to ground as shown in Figure 3.

\[
\Delta V_e(\text{MAX}) = (V_p) \left( \frac{4.5}{2f_{cm}} \right) \text{ fCLK}
\]

or

\[
V_p = \frac{(6 \times 10^{-3})(640 \times 10^3)}{(6.28)(60)(4.5)}
\]

which gives

\[
V_p \approx 1.9\text{V}
\]

The allowed range of analog input voltages usually places more severe restrictions on input common-mode noise levels.

An analog input voltage with a reduced span and a relatively large zero offset can be handled easily by making use of the differential input (see section 2.4 Reference Voltage).
**Functional Description (Continued)**

The voltage on this capacitance is switched and will result in currents entering the \( V_{IN}^+ \) input pin and leaving the \( V_{IN}^- \) input which will depend on the analog differential input voltage levels. These current transients occur at the leading edge of the internal clocks. They rapidly decay and do not cause errors as the on-chip comparator is strobed at the end of the clock period.

**Fault Mode**

If the voltage source applied to the \( V_{IN}^+ \) or \( V_{IN}^- \) pin exceeds the allowed operating range of \( V_{CC} \pm 50 \text{ mV} \), large input currents can flow through a parasitic diode to the \( V_{CC} \) pin. If these currents can exceed the 1 mA max allowed spec, an external diode (1N914) should be added to bypass this current to the \( V_{CC} \) pin (with the current bypassed with this diode, the voltage at the \( V_{IN}^+ \) pin can exceed the \( V_{CC} \) voltage by the forward voltage of this diode).

2.3.2 Input Bypass Capacitors

Bypass capacitors at the inputs will average these charges and cause a DC current to flow through the output resistances of the analog signal sources. This charge pumping action is worse for continuous conversions with the \( V_{IN}^+ \) input voltage at full-scale. For continuous conversions with a 640 kHz clock frequency with the \( V_{IN}^+ \) input at 5V, this DC current is at a maximum of approximately 5 \( \mu \text{A} \). Therefore, bypass capacitors should not be used at the analog inputs or the \( V_{REF}/2 \) pin for high resistance sources (> 1 k\( \Omega \)). If input bypass capacitors are necessary for noise filtering and high source resistance is desirable to minimize capacitor size, the detrimental effects of the voltage drop across this input resistance, which is due to the average value of the input current, can be eliminated with a full-scale adjustment while the given source resistor and input bypass capacitor are both in place. This is possible because the average value of the input current is a precise linear function of the differential input voltage.

2.3.3 Input Source Resistance

Large values of source resistance where an input bypass capacitor is not used, will not cause errors as the input currents settle out prior to the comparison time. If a low pass filter is required in the system, use a low valued series resistor (≤ 1 k\( \Omega \)) for a passive RC section or add an op amp RC active low pass filter. For low source resistance applications, (≤ 1 k\( \Omega \)), a 0.1 \( \mu \text{A} \) bypass capacitor at the inputs will prevent noise pickup due to series lead inductance of a long wire. A 100\( \Omega \) series resistor can be used to isolate this capacitor—both the R and C are placed outside the feedback loop—from the output of an op amp, if used.

2.3.4 Noise

The leads to the analog inputs (pin 6 and 7) should be kept as short as possible to minimize input noise coupling. Both noise and undesired digital clock coupling to these inputs can cause system errors. The source resistance for these inputs should, in general, be kept below 5 k\( \Omega \). Larger values of source resistance can cause undesired system noise pickup. Input bypass capacitors, placed from the analog inputs to ground, will eliminate system noise pickup but can create analog scale errors as these capacitors will average the transient input switching currents of the A/D (see section 2.3.1.). This scale error depends on both a large source resistance and the use of an input bypass capacitor. This error can be eliminated by doing a full-scale adjustment of the A/D (adjust \( V_{REF}/2 \) for a proper full-scale reading—see section 2.5.2 on Full-Scale Adjustment) with the source resistance and input bypass capacitor in place.

2.4 Reference Voltage

2.4.1 Span Adjust

For maximum applications flexibility, these A/Ds have been designed to accommodate a 5 V\( _{DC} \), 2.5 V\( _{DC} \) or an adjusted voltage reference. This has been achieved in the design of the IC as shown in Figure 4.

![FIGURE 4. The \( V_{REFERENCE} \) Design on the IC](image)

Notice that the reference voltage for the IC is either \( 1/2 \) of the voltage applied to the \( V_{CC} \) supply pin, or is equal to the voltage that is externally forced at the \( V_{REF}/2 \) pin. This allows for a ratiometric voltage reference using the \( V_{CC} \) supply, a 5 V\( _{DC} \) reference voltage can be used for the \( V_{CC} \) supply or a voltage less than 2.5 V\( _{DC} \) can be applied to the \( V_{REF}/2 \) input for increased application flexibility. The internal gain to the \( V_{REF}/2 \) input is 2, making the full-scale differential input voltage twice the voltage at pin 9. An example of the use of an adjusted reference voltage is to accommodate a reduced span—or dynamic voltage range of the analog input voltage. If the analog input voltage were to range from 0.5 V\( _{DC} \) to 3.5 V\( _{DC} \), instead of 0V to 5 V\( _{DC} \), the span would be 3V as shown in Figure 5. With 0.5 V\( _{DC} \) applied to the \( V_{IN}^- \) pin to absorb the offset, the reference voltage can be made equal to \( 1/2 \) of the 3V span or 1.5 V\( _{DC} \). The A/D now will encode the \( V_{IN}^+ \) signal from 0.5V to 3.5 V with the 0.5V input corresponding to zero and the 3.5 V\( _{DC} \) input corresponding to full-scale. The full 8 bits of resolution are therefore applied over this reduced analog input voltage range.
**Functional Description** (Continued)

*a* Add if $V_{REF}/2 \leq V_{DC}$ with LM358 to draw 3 mA to ground.

---

**2.4.2 Reference Accuracy Requirements**

The converter can be operated in a ratiometric mode or an absolute mode. In ratiometric converter applications, the magnitude of the reference voltage is a factor in both the output of the source transducer and the output of the A/D converter and therefore cancels out in the final digital output code. The ADC0805 is specified particularly for use in ratiometric applications with no adjustments required. In absolute conversion applications, both the initial value and the temperature stability of the reference voltage are important factors in the accuracy of the A/D converter. For $V_{REF}/2$ voltages of 2.4 $V_{DC}$ nominal value, initial errors of $\pm 10 mV_{DC}$ will cause conversion errors of $\pm 1$ LSB due to the gain of 2 of the $V_{REF}/2$ input. In reduced span applications, the initial value and the stability of the $V_{REF}/2$ input voltage become even more important. For example, if the span is reduced to 2.5V, the analog input LSB voltage value is correspondingly reduced from 20 mV to 10 mV and 1 LSB at the $V_{REF}/2$ input becomes 5 mV. As can be seen, this reduces the allowed initial tolerance of the reference voltage and requires correspondingly less absolute change with temperature variations. Note that spans smaller than 2.5V place even tighter requirements on the initial accuracy and stability of the reference source.

In general, the magnitude of the reference voltage will require an initial adjustment. Errors due to an improper value of reference voltage appear as full-scale errors in the A/D transfer function. IC voltage regulators may be used for references if the ambient temperature changes are not excessive. The LM336B 2.5V IC reference diode (from National Semiconductor) has a temperature stability of 1.8 mV typ (6 mV max) over $0^\circ C \leq T_A \leq +70^\circ C$. Other temperature range parts are also available.

---

**2.5 Errors and Reference Voltage Adjustments**

**2.5.1 Zero Error**

The zero of the A/D does not require adjustment. If the minimum analog input voltage, $V_{IN(MIN)}$, is not ground, a zero offset can be done. The converter can be made to output 0000 0000 digital code for this minimum input voltage by biasing the A/D $V_{IN}(-)$ input at this $V_{IN(MIN)}$ value (see Applications section). This utilizes the differential mode operation of the A/D.

The zero error of the A/D converter relates to the location of the first riser of the transfer function and can be measured by grounding the $V_{IN}(-)$ input and applying a small magnitude positive voltage to the $V_{IN}(+)$. Zero error is the difference between the actual DC input voltage that is necessary to just cause an output digital code transition from 0000 0000 to 0000 0001 and the ideal $1/2$ LSB value ($9.8 mV$ for $V_{REF}/2 = 2.500 V_{DC}$).

**2.5.2 Full-Scale**

The full-scale adjustment can be made by applying a differential input voltage that is $1/2$ LSB less than the desired analog full-scale voltage range and then adjusting the magnitude of the $V_{REF}/2$ input (pin 9 or the $V_{CC}$ supply if pin 9 is not used) for a digital output code that is just changing from 1111 1110 to 1111 1111.
Functional Description (Continued)

2.5.3 Adjusting for an Arbitrary Analog Input Voltage Range
If the analog zero voltage of the A/D is shifted away from ground (for example, to accommodate an analog input signal that does not go to ground) this new zero reference should be properly adjusted first. A \( V_{IN}^{(+)} \) voltage that equals this desired zero reference plus \( \frac{1}{2} \) LSB (where the LSB is calculated for the desired analog span, \( 1 \) LSB – analog span/256) is applied to pin 6 and the zero reference voltage at pin 7 should then be adjusted to just obtain the 00HEX to 01HEX code transition.

The full-scale adjustment should then be made (with the proper \( V_{IN}^{(-)} \) voltage applied) by forcing a voltage to the \( V_{IN}^{(+)} \) input which is given by:

\[
V_{IN}^{(+)}_{fs \ adj} = V_{MAX} - 1.5 \left( \frac{V_{MAX} - V_{MIN}}{256} \right)
\]

where:
- \( V_{MAX} \) – The high end of the analog input range
- \( V_{MIN} \) – The low end (the offset zero) of the analog range.

(Both are ground referenced.)

The \( V_{REF}/2 \) (or \( V_{CC} \)) voltage is then adjusted to provide a code change from FEHEX to FFHEX. This completes the adjustment procedure.

2.6 Clocking Option
The clock for the A/D can be derived from the CPU clock or an external RC can be added to provide self-clocking. The CLK IN (pin 4) makes use of a Schmitt trigger as shown in Figure 6.

![FIGURE 6. Self-Clocking the A/D](image)

Heavy capacitive or DC loading of the clock R pin should be avoided as this will disturb normal converter operation. Loads less than 50 pF, such as driving up to 7 A/D converter clock inputs from a single clock R pin of 1 converter, are allowed. For larger clock line loading, a CMOS or low power TTL buffer or PNP input logic should be used to minimize the loading on the clock R pin (do not use a standard TTL buffer).

2.7 Restart During a Conversion
If the A/D is restarted (\( \text{CS and WR} \) go low and return high) during a conversion, the converter is reset and a new conversion is started. The output data latch is not updated if the conversion in process is not allowed to be completed, therefore the data of the previous conversion remains in this latch. The INTR output simply remains at the “1” level.

2.8 Continuous Conversions
For operation in the free-running mode an initializing pulse should be used, following power-up, to ensure circuit operation. In this application, the \( \text{CS} \) input is grounded and the \( \text{WR} \) input is tied to the INTR output. This \( \text{WR} \) and INTR node should be momentarily forced to logic low following a power-up cycle to guarantee operation.

2.9 Driving the Data Bus
This MOS A/D, like MOS microprocessors and memories, will require a bus driver when the total capacitance of the data bus gets large. Other circuitry, which is tied to the data bus, will add to the total capacitive loading, even in TRI-STATE (high impedance mode). Backplane bussing also greatly adds to the stray capacitance of the data bus.

There are some alternatives available to the designer to handle this problem. Basically, the capacitive loading of the data bus slows down the response time, even though DC specifications are still met. For systems operating with a relatively slow CPU clock frequency, more time is available in which to establish proper logic levels on the bus and therefore higher capacitive loads can be driven (see typical characteristics curves).

At higher CPU clock frequencies time can be extended for I/O reads (and/or writes) by inserting wait states (8080) or using clock extending circuits (6800).

Finally, if time is short and capacitive loading is high, external bus drivers must be used. These can be TRI-STATE buffers (low power Schottky such as the DM74LS240 series is recommended) or special higher drive current products which are designed as bus drivers. High current bipolar bus drivers with PNP inputs are recommended.

2.10 Power Supplies
Noise spikes on the \( V_{CC} \) supply line can cause conversion errors as the comparator will respond to this noise. A low inductance tantalum filter capacitor should be used close to the converter \( V_{CC} \) pin and values of 1 \( \mu \)F or greater are recommended. If an unregulated voltage is available in the system, a separate LM340LAZ-5.0, TO-92, 5V voltage regulator for the converter (and other analog circuitry) will greatly reduce digital noise on the \( V_{CC} \) supply.

2.11 Wiring and Hook-Up Precautions
Standard digital wire wrap sockets are not satisfactory for breadboarding this A/D converter. Sockets on PC boards can be used and all logic signal wires and leads should be grouped and kept as far away as possible from the analog signal leads. Exposed leads to the analog inputs can cause undesired digital noise and hum pickup, therefore shielded leads may be necessary in many applications.
A single point analog ground that is separate from the logic ground points should be used. The power supply bypass capacitor and the self-clocking capacitor (if used) should both be returned to digital ground. Any \( V_{\text{REF/2}} \) bypass capacitors, analog input filter capacitors, or input signal shielding should be returned to the analog ground point. A test for proper grounding is to measure the zero error of the A/D converter. Zero errors in excess of \( \frac{1}{4} \text{LSB} \) can usually be traced to improper board layout and wiring (see section 2.5.1 for measuring the zero error).

3.0 TESTING THE A/D CONVERTER

There are many degrees of complexity associated with testing an A/D converter. One of the simplest tests is to apply a known analog input voltage to the converter and use LEDs to display the resulting digital output code as shown in Figure 7.

For ease of testing, the \( V_{\text{REF/2}} \) (pin 9) should be supplied with 2.560 V DC and a \( V_{\text{CC}} \) supply voltage of 5.12 V DC should be used. This provides an LSB value of 20 mV.

If a full-scale adjustment is to be made, an analog input voltage of 5.090 V DC (5.120 – 1.5\( \times \frac{1}{2} \) LSB) should be applied to the \( V_{\text{IN(a)}} \) with the \( V_{\text{IN(b)}} \) pin grounded. The value of \( V_{\text{REF/2}} \) input voltage should then be adjusted until the digital output code is just changing from 1111 1110 to 1111 1111. This value of \( V_{\text{REF/2}} \) should then be used for all the tests.

The digital output LED display can be decoded by dividing the 8 bits into 2 hex characters, the 4 most significant (MS) and the 4 least significant (LS). Table I shows the fractional binary equivalent of these two 4-bit groups. By adding the voltages obtained from the “VMS” and “VLS” columns in Table I, the nominal value of the digital display (when \( V_{\text{REF/2}} = 2.560 \text{V} \)) can be determined. For example, for an output LED display of 1011 0110 or B6 (in hex), the voltage values from the table are 3.520 + 0.120 or 3.640 VDC. These voltage values represent the center-values of a perfect A/D converter. The effects of quantization error have to be accounted for in the interpretation of the test results.

For a higher speed test system, or to obtain plotted data, a digital-to-analog converter is needed for the test set-up. An accurate 10-bit DAC can serve as the precision voltage source for the A/D. Errors of the A/D under test can be expressed as either analog voltages or differences in 2 digital words.

A basic A/D tester that uses a DAC and provides the error as an analog output voltage is shown in Figure 6. The 2 op amps can be eliminated if a lab DVM with a numerical subtraction feature is available to read the difference voltage, “\( A-C \)”, directly. The analog input voltage can be supplied by a low frequency ramp generator and an X-Y plotter can be used to provide analog error (Y axis) versus analog input (X axis).

For operation with a microprocessor or a computer-based test system, it is more convenient to present the errors digitally. This can be done with the circuit of Figure 9, where the output code transitions can be detected as the 10-bit DAC is incremented. This provides \( \frac{1}{4} \) LSB steps for the 8-bit A/D under test. If the results of this test are automatically plotted with the analog input on the X axis and the error (in LSB’s) as the Y axis, a useful transfer function of the A/D under test results. For acceptance testing, the plot is not necessary and the testing speed can be increased by establishing internal limits on the allowed error for each code.

4.0 MICROPROCESSOR INTERFACING

To discuss the interface with 8080A and 6800 microprocessors, a common sample subroutine structure is used. The microprocessor starts the A/D, reads and stores the results of 16 successive conversions, then returns to the user’s program. The 16 data bytes are stored in 16 successive memory locations. All Data and Addresses will be given in hexadecimal form. Software and hardware details are provided separately for each type of microprocessor.

4.1 Interfacing 8080 Microprocessor Derivatives (8048, 8085)

This converter has been designed to directly interface with derivatives of the 8080 microprocessor. The A/D can be mapped into memory space (using standard memory address decoding for \( \text{CS} \) and the \( \text{MEMR} \) and \( \text{MEMW} \) strobes) or it can be controlled as an I/O device by using the \( \text{IOTR} \) and \( \text{IOTW} \) strobes and decoding the address bits \( A_0 \rightarrow A_7 \) (or address bits \( A_8 \rightarrow A_{15} \) as they will contain the same 8-bit address information) to obtain the \( \text{CS} \) input. Using the I/O space provides 256 additional addresses and may allow a simpler 8-bit address decoder but the data can only be input to the accumulator. To make use of the additional memory reference instructions, the A/D should be mapped into memory space. An example of an A/D in I/O space is shown in Figure 10.
**Functional Description** (Continued)

![FIGURE 8. A/D Tester with Analog Error Output](image)

![FIGURE 9. Basic "Digital" A/D Tester](image)

**TABLE I. DECODING THE DIGITAL OUTPUT LEDs**

<table>
<thead>
<tr>
<th>HEX</th>
<th>BINARY</th>
<th>FRACTIONAL BINARY VALUE FOR</th>
<th>OUTPUT VOLTAGE CENTER VALUES WITH $V_{\text{REF}}/2 = 2.560\ V_{\text{DC}}$</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>MS GROUP</td>
<td>LS GROUP</td>
</tr>
<tr>
<td>F</td>
<td>1 1 1 1</td>
<td>15/16</td>
<td>15/256</td>
</tr>
<tr>
<td>E</td>
<td>1 1 1 0</td>
<td>7/8</td>
<td>7/128</td>
</tr>
<tr>
<td>D</td>
<td>1 1 0 1</td>
<td>13/16</td>
<td>13/256</td>
</tr>
<tr>
<td>C</td>
<td>1 1 0 0</td>
<td>3/4</td>
<td>3/64</td>
</tr>
<tr>
<td>B</td>
<td>1 0 1 1</td>
<td>11/16</td>
<td>11/256</td>
</tr>
<tr>
<td>A</td>
<td>1 0 1 0</td>
<td>5/8</td>
<td>5/128</td>
</tr>
<tr>
<td>9</td>
<td>1 0 0 1</td>
<td>9/16</td>
<td>9/256</td>
</tr>
<tr>
<td>8</td>
<td>1 0 0 0</td>
<td>1/2</td>
<td>1/32</td>
</tr>
<tr>
<td>7</td>
<td>0 1 1 1</td>
<td>7/16</td>
<td>7/256</td>
</tr>
<tr>
<td>6</td>
<td>0 1 1 0</td>
<td>3/8</td>
<td>3/128</td>
</tr>
<tr>
<td>5</td>
<td>0 1 0 1</td>
<td>5/16</td>
<td>5/256</td>
</tr>
<tr>
<td>4</td>
<td>0 1 0 0</td>
<td>1/4</td>
<td>1/64</td>
</tr>
<tr>
<td>3</td>
<td>0 0 1 1</td>
<td>3/16</td>
<td>3/256</td>
</tr>
<tr>
<td>2</td>
<td>0 0 1 0</td>
<td>1/8</td>
<td>1/128</td>
</tr>
<tr>
<td>1</td>
<td>0 0 0 1</td>
<td>1/16</td>
<td>1/256</td>
</tr>
<tr>
<td>0</td>
<td>0 0 0 0</td>
<td>0</td>
<td>0</td>
</tr>
</tbody>
</table>

*Display Output = VMS Group + VLS Group
Note 1: Pin numbers for the DP8228 system controller, others are INS8080A.

Note 2: Pin 23 of the INS8228 must be tied to 12V through a 4.7k resistor to generate the RST 7 instruction when an interrupt is acknowledged as required by the accompanying sample program.

FIGURE 10. ADC0801–INS8080A CPU Interface

SAMPLE PROGRAM FOR FIGURE 10 ADC0801–INS8080A CPU INTERFACE

0038 C3 00 03 RST 7: JMP LD DATA

* * * *

0100 21 00 02 START: LXI H 0200H ; HL pair will point to data storage locations

0103 31 00 04 RETURN: LXI SP 0400H ; Initialize stack pointer (Note 1)

0106 7D MOV A, L ; Test # of bytes entered

0107 FE OF CPI OF H ; If # ≤ 16, JMP to

0109 CA 13 01 JZ CONT ; user program

010C D3 E0 OUT E0 H ; Start A/D

010E FB EI ; Enable interrupt

010F 00 LOOP: NOP ; Loop until end of

0110 C3 0F 01 JMP LOOP ; conversion

0113 • CONT: •

* * * *

(Use program to

* process data)

* * * *

0500 DB E0 LD DATA: INE0H ; Load data into accumulator

0502 77 MOV W, A ; Store data

0503 23 INX H ; Increment storage pointer

0504 C3 03 01 JMP RETURN

Note 1: The stack pointer must be dimensioned because a RST 7 instruction pushes the PC onto the stack.

Note 2: All address used were arbitrarily chosen.
Functional Description (Continued)

The standard control bus signals of the 8080 CS, RD, and WR can be directly wired to the digital control inputs of the A/D and the bus timing requirements are met to allow both starting the converter and outputting the data onto the data bus. A bus driver should be used for larger microprocessor systems where the data bus leaves the PC board and/or must drive capacitive loads larger than 100 pF.

4.1.1 Sample 8080A CPU Interfacing Circuitry and Program

The following sample program and associated hardware shown in Figure 10 may be used to input data from the converter to the INS8080A CPU chip set (comprised of the INS8080A microprocessor, the INS8228 system controller and the INS8224 clock generator). For simplicity, the A/D is controlled as an I/O device, specifically an 8-bit bi-directional port located at an arbitrarily chosen port address, E0. The TRI-STATE output capability of the A/D eliminates the need for a peripheral interface device, however address decoding is still required to generate the appropriate CS for the converter.

It is important to note that in systems where the A/D converter is 1-of-8 or less I/O mapped devices, no address decoding circuitry is necessary. Each of the 8 address bits (A0 to A7) can be directly used as CS inputs—one for each I/O device.

4.1.2 INS8048 Interface

The INS8048 interface technique with the ADC0801 series (see Figure 11) is simpler than the 8080A CPU interface. There are 24 I/O lines and three test input lines in the 8048. With these extra I/O lines available, one of the I/O lines (bit 0 of port 1) is used as the chip select signal to the A/D, thus eliminating the use of an external address decoder. Bus control signals RD, WR, and INT of the 8048 are tied directly to the A/D. The 16 converted data words are stored at on-chip RAM locations from 20 to 2F (Hex). The RD and WR signals are generated by reading from and writing into a dummy address, respectively. A sample interface program is shown below.

```
04 10 JMP 10H ; Program starts at addr 10
04 50 JMP 50H ; Interrupt jump vector
ORG 3H
ORG 10H ; Main program
99 FE ANL P1, #0FEH ; Chip select
81 MOVX A, @R1 ; Read in the 1st data
89 01 START: ORL P1, #1 ; Set port pin high
B8 20 MOV R0, #20H ; Data address
B9 FF MOV R1, #0FFH ; Dummy address
BA 10 MOV R2, #10H ; Counter for 16 bytes
23 FF AGAIN: MOV A, #0FFH ; Set ACC for intr loop
99 FE ANL P1, #0FEH ; Send CS (bit 0 of P1)
91 MOVX @R1, A ; Send WR out
05 EN I ; Enable interrupt
86 21 LOOP: JNZ LOOP ; Wait for interrupt
EA 1B DJNZ R2, AGAIN ; If 16 bytes are read
00 NOP ; go to user’s program
00 NOP
ORG 50H
81 INDATA: MOVX A, @R1 ; Input data, CS still low
A0 MOV @R0, A ; Store in memory
18 INC R0 ; Increment storage counter
89 01 ORL P1, #1 ; Reset CS signal
27 CLR A ; Clear ACC to get out of
93 RETR ; the interrupt loop
```

FIGURE 11. INS8048 Interface

SAMPLE PROGRAM FOR FIGURE 11 INS8048 INTERFACE
4.2 Interfacing the Z-80

The Z-80 control bus is slightly different from that of the 8080. General RD and WR strobes are provided and separate memory request, MREQ, and I/O request, IORQ, signals are used which have to be combined with the generalized strobes to provide the equivalent 8080 signals. An advantage of operating the A/D in I/O space with the Z-80 is that the CPU will automatically insert one wait state (the RD and WR strobes are extended one clock period) to allow more time for the I/O devices to respond. Logic to map the A/D in I/O space is shown in Figure 13.

Additional I/O advantages exist as software DMA routines are available and use can be made of the output data transfer which exists on the upper 8 address lines (A8 to A15) during I/O input instructions. For example, MUX channel selection for the A/D can be accomplished with this operating mode.

4.3 Interfacing 6800 Microprocessor Derivatives (6502, etc.)

The control bus for the 6800 microprocessor derivatives does not use the RD and WR strobe signals. Instead it employs a single R/W line and additional timing, if needed, can be derived from the 8/2 clock. All I/O devices are memory mapped in the 6800 system, and a special signal, VMA, indicates that the current address is valid. Figure 14 shows an interface schematic where the A/D is memory mapped in the 6800 system. For simplicity, the CS decoding is shown using 1/2 DM8092. Note that in many 6800 systems, an already decoded 4/5 line is brought out to the common bus at pin 21. This can be tied directly to the CS pin of the A/D, provided that no other devices are addressed at HX ADDR: 4XXX or 5XXX.

The following subroutine performs essentially the same function as in the case of the 8080A interface and it can be called from anywhere in the user’s program.

In Figure 15 the ADC0801 series is interfaced to the M6800 microprocessor through (the arbitrarily chosen) Port B of the MC6820 or MC6821 Peripheral Interface Adapter, (PIA). Here the CS pin of the A/D is grounded since the PIA is already memory mapped in the M6800 system and no CS decoding is necessary. Also notice that the A/D output data lines are connected to the microprocessor bus under program control through the PIA and therefore the A/D RD pin can be grounded.

A sample interface program equivalent to the previous one is shown below Figure 15. The PIA Data and Control Registers of Port B are located at HEX addresses 8006 and 8007, respectively.

5.0 GENERAL APPLICATIONS

The following applications show some interesting uses for the A/D. The fact that one particular microprocessor is used is not meant to be restrictive. Each of these application circuits would have its counterpart using any microprocessor that is desired.

5.1 Multiple ADC0801 Series to M6800 CPU Interface

To transfer analog data from several channels to a single microprocessor system, a multiple converter scheme presents several advantages over the conventional multiplexer single-converter approach. With the ADC0801 series, the differential inputs allow individual span adjustment for each channel. Furthermore, all analog input channels are sensed simultaneously, which essentially divides the microprocessor’s total system servicing time by the number of channels, since all conversions occur simultaneously. This scheme is shown in Figure 16.
Functional Description (Continued)

**SAMPLE PROGRAM FOR FIGURE 14 ADC0801-MC6800 CPU INTERFACE**

```
0010 DF 36 DATAIN STX TEMP2 ; Save contents of X
0012 CE 00 2C LDX #$002C ; Upon IRQ low CPU
0015 FF FF F8 STX $FFF8 ; jumps to 002C
0018 B7 50 00 STAA $5000 ; Start ADC0801
001A 0E CLI
001C 3E CONVRT WAI ; Wait for interrupt
001D DE 34 LDX TEMP1
001F 8C 02 0F CFX #$020F ; Is final data stored?
0022 27 14 BEQ ENDP
0024 B7 50 00 STAA $5000 ; Restarts ADC0801
0027 08 INX
0028 DF 34 STX TEMP1
002A 20 F0 BRA CONVRT
002C DE 34 INTRPT LDX TEMP1
002E B6 50 00 LDAA $5000 ; Read data
0031 A7 00 STAA X ; Store it at X
0033 38 RTI
0034 02 00 TEMP1 FDB $0020 ; Starting address for data storage
0036 00 00 TEMP2 FDB $0000
0038 CE 02 00 ENDP LDX #$0200 ; Reinitialize TEMP1
003A DF 34 STX TEMP1
003C DE 36 LDX TEMP2
003E 39 RTS ; Return from subroutine
              ; To user's program
```

**Note 1:** In order for the microprocessor to service subroutines and interrupts, the stack pointer must be dimensioned in the user’s program.

---

**FIGURE 15. ADC0801–MC6820 PIA Interface**

---

TL/H/5671–25
Functional Description (Continued)

SAMPLE PROGRAM FOR FIGURE 15 ADC0801–MC6820 PIA INTERFACE

```
0010 CE 00 38 DATAIN LDX #$0038 ; Upon IRQ low CPU
0013 FF FF FF STX #$FFF8 ; Jumps to 0038
0016 B6 80 06 LDAA PIAORB ; Clear possible IRQ flags
0019 4F CLRA
001A B7 80 07 STAA PIACRB
001D B7 80 06 STAA PIAORB ; Set Port B as input
0020 0E CLI
0021 C6 34 LDAB #$34
0023 86 3D LDAA #$3D
0025 F7 80 07 CONVRT STAB PIACRB ; Starts ADC0801
0028 B7 80 07 STAA PIACRB
002B 3E WAI ; Wait for interrupt
002C DE 40 LDX TEMP1
002E 8C 02 0F CFX #$020F ; Is final data stored?
0031 27 0F BEQ ENDP
0033 08 INX
0034 DF 40 STX TEMP1
0036 20 ED BRA CONVRT
0038 DE 40 INTRPT LDX TEMP1 ; Read data in
003A B6 80 06 LDAA PIAORB X ; Store it at X
003D A7 00 STAA PIAORB
003F 38 RTI
0040 02 00 TEMP1 FDX $0200 ; Starting address for data storage
0042 CE 02 00 ENDP LDX #$0200 ; Reinitialize TEMP1
0045 DF 40 STX TEMP1
0047 39 RTS ; Return from subroutine
PIAORB EQU $8006 ; To user’s program
PIACRB EQU $8007
```

The following schematic and sample subroutine (DATA IN) may be used to interface (up to) 8 ADC0801’s directly to the MC6800 CPU. This scheme can easily be extended to allow the interface of more converters. In this configuration the converters are (arbitrarily) located at HEX address 5000 in the MC6800 memory space. To save components, the clock signal is derived from just one RC pair on the first converter. This output drives the other A/Ds.

All the converters are started simultaneously with a STORE instruction at HEX address 5000. Note that any other HEX address of the form SXXX will be decoded by the circuit, pulling all the CS inputs low. This can easily be avoided by using a more definitive address decoding scheme. All the interrupts are ORed together to insure that all A/Ds have completed their conversion before the microprocessor is interrupted.

CPU, starts all the converters simultaneously and waits for the interrupt signal. Upon receiving the interrupt, it reads the converters (from HEX addresses 5000 through 5007) and stores the data successively at (arbitrarily chosen) HEX addresses 0200 to 0207, before returning to the user’s program. All CPU registers then recover the original data they had before servicing DATA IN.

### 5.2 Auto-Zeroed Differential Transducer Amplifier and A/D Converter

The differential inputs of the ADC0801 series eliminate the need to perform a differential to single ended conversion for a differential transducer. Thus, one op amp can be eliminated since the differential to single ended conversion is provided by the differential input of the ADC0801 series. In general, a transducer preamp is required to take advantage of the full A/D converter input dynamic range.
FIGURE 16. Interfacing Multiple A/Ds in an MC6800 System

SAMPLE PROGRAM FOR FIGURE 16 INTERFACING MULTIPLE A/Ds IN AN MC6800 SYSTEM

<table>
<thead>
<tr>
<th>ADDRESS</th>
<th>HEX CODE</th>
<th>MNEMONICS</th>
<th>COMMENTS</th>
</tr>
</thead>
<tbody>
<tr>
<td>0010</td>
<td>DF 44</td>
<td>DATAIN</td>
<td>STX TEMP ;; Save Contents of X</td>
</tr>
<tr>
<td>0012</td>
<td>CE 00 2A</td>
<td>LDX</td>
<td>#$002A ;; Upon INT LOW CPU</td>
</tr>
<tr>
<td>0015</td>
<td>FFFF F8</td>
<td>STX</td>
<td>$FFFF ;; Jumps to 002A</td>
</tr>
<tr>
<td>0018</td>
<td>B7 50 00</td>
<td>STAA</td>
<td>$5000 ;; Starts all A/D's</td>
</tr>
<tr>
<td>001B</td>
<td>CE 02 00</td>
<td>LDX</td>
<td>$5000</td>
</tr>
<tr>
<td>001C</td>
<td>3E</td>
<td>CLI</td>
<td>Wait for interrupt</td>
</tr>
<tr>
<td>0020</td>
<td>CE 00 00</td>
<td>LDX</td>
<td>#$5000</td>
</tr>
<tr>
<td>0022</td>
<td>DF 40</td>
<td>STX</td>
<td>INDEX1 ;; Reset both INDEX</td>
</tr>
<tr>
<td>0025</td>
<td>DF 42</td>
<td>STX</td>
<td>INDEX2 ;; addresses</td>
</tr>
<tr>
<td>0027</td>
<td>DE 44</td>
<td>LDX</td>
<td>TEMP</td>
</tr>
<tr>
<td>0029</td>
<td>39</td>
<td>RTS</td>
<td>Return from subroutine</td>
</tr>
<tr>
<td>002A</td>
<td>DE 40</td>
<td>INTRPT</td>
<td>LDX INDEX1 ;; INDEX1 → X</td>
</tr>
<tr>
<td>002C</td>
<td>A6 00</td>
<td>LDAA</td>
<td>X ;; Read data in from A/D at X</td>
</tr>
<tr>
<td>002E</td>
<td>08</td>
<td>INX</td>
<td>Increment X by one</td>
</tr>
<tr>
<td>002F</td>
<td>DF 40</td>
<td>STX</td>
<td>INDEX1 ;; X → INDEX1</td>
</tr>
<tr>
<td>0031</td>
<td>DE 42</td>
<td>LDX</td>
<td>INDEX2 ;; INDEX2 → X</td>
</tr>
</tbody>
</table>
Functional Description (Continued)

SAMPLE PROGRAM FOR FIGURE 16 INTERFACING MULTIPLE A/Ds IN AN MC6800 SYSTEM

<table>
<thead>
<tr>
<th>ADDRESS</th>
<th>HEX CODE</th>
<th>MNEMONICS</th>
<th>COMMENTS</th>
</tr>
</thead>
<tbody>
<tr>
<td>0033</td>
<td>A7 00</td>
<td>STAA X</td>
<td>Store data at X</td>
</tr>
<tr>
<td>0035</td>
<td>8C 02 07</td>
<td>CPX #0207</td>
<td>Have all A/D’s been read?</td>
</tr>
<tr>
<td>0038</td>
<td>27 05</td>
<td>BEX RETURN</td>
<td>Yes: branch to RETURN</td>
</tr>
<tr>
<td>003A</td>
<td>08</td>
<td>INX INDEX2</td>
<td>No: increment X by one</td>
</tr>
<tr>
<td>003B</td>
<td>DF 42</td>
<td>STX INDEX2</td>
<td>; X → INDEX2</td>
</tr>
<tr>
<td>003D</td>
<td>20 0B</td>
<td>RETURN RTI</td>
<td>Branch to 002A</td>
</tr>
<tr>
<td>003F</td>
<td>3D</td>
<td>INK INDEX2</td>
<td>Starting address for A/D</td>
</tr>
<tr>
<td>0040</td>
<td>50 00</td>
<td>INDEX1 FDB $5000</td>
<td>Starting address for data storage</td>
</tr>
<tr>
<td>0042</td>
<td>02 00</td>
<td>INDEX2 FDB $0200</td>
<td>Starting address for data storage</td>
</tr>
<tr>
<td>0044</td>
<td>00 00</td>
<td>TEMP FDB $0000</td>
<td></td>
</tr>
</tbody>
</table>

Note: In order for the microprocessor to service subroutines and interrupts, the stack pointer must be dimensioned in the user’s program.

For amplification of DC input signals, a major system error is the input offset voltage of the amplifiers used for the preamp. Figure 17 is a gain of 100 differential preamp whose offset voltage errors will be cancelled by a zeroing subroutine which is performed by the INS8080A microprocessor system. The total allowable input offset voltage error for this preamp is only 50 μV for 1/4 LSB error. This would obviously require very precise amplifiers. The expression for the differential output voltage of the preamp is:

\[
V_O = \left( V_{IN(+)} - V_{IN(-)} \right) \left( 1 + \frac{2R_2}{R_1} \right)
\]

where Ix is the current through resistor Rx. All of the offset error terms can be cancelled by making ±IₓRx = VOS1 + VOS3 - VOS2. This is the principle of this auto-zeroing scheme.

The INS8080A uses the 3 I/O ports of an INS8255 Programmable Peripheral Interface (PPI) to control the auto-zeroing and input data from the ADC0801 as shown in Figure 18. The PPI is programmed for basic I/O operation (mode 0) with Port A being an input port and Ports B and C being output ports. Two bits of Port C are used to alternately open or close the 2 switches at the input of the preamp. Switch SW1 is closed to force the preamp’s differential input to be zero during the zeroing subroutine and then opened and SW2 is then closed for conversion of the actual differential input signal. Using 2 switches in this manner eliminates concern for the ON resistance of the switches as they must conduct only the input bias current of the input amplifiers.

Output Port B is used as a successive approximation register by the 8080 and the binary scaled resistors in series with each output bit create a D/A converter. During the zeroing subroutine, the voltage at Vx increases or decreases as required to make the differential output voltage equal to zero. This is accomplished by ensuring that the voltage at the output of A1 is approximately 2.5V so that a logic “1” (5V) on any output of Port B will source current into node VX thus raising the voltage at VX and making the output differential more negative. Conversely, a logic “0” (0V) will pull current out of node VX and decrease the voltage, causing the differential output to become more positive. For the resistor values shown, VX can move ±12 mV with a resolution of 50 μV, which will null the offset error term to 1/4 LSB of full-scale for the ADC0801. It is important that the voltage levels that drive the auto-zero resistors be constant. Also, for symmetry, a logic swing of 0V to 5V is convenient. To achieve this, a CMOS buffer is used for the logic output signals of Port B and this CMOS package is powered with a stable 5V source. Buffer amplifier A1 is necessary so that it can source or sink the D/A output current.
Note 1: R2 = 49.5 R1
Note 2: Switches are LMC13334 CMOS analog switches.
Note 3: The 9 resistors used in the auto-zero section can be ±5% tolerance.

FIGURE 17. Gain of 100 Differential Transducer Preamp

FIGURE 18. Microprocessor Interface Circuitry for Differential Preamp
A flow chart for the zeroing subroutine is shown in Figure 19. It must be noted that the ADC0801 series will output an all zero code when it converts a negative input \([V_{IN}(\text{b}) < V_{IN}(\text{a})]\). Also, a logic inversion exists as all of the I/O ports are buffered with inverting gates.

Basically, if the data read is zero, the differential output voltage is negative, so a bit in Port B is cleared to pull \(V_X\) more negative which will make the output more positive for the next conversion. If the data read is not zero, the output voltage is positive so a bit in Port B is set to make \(V_X\) more positive and the output more negative. This continues for 8 approximations and the differential output eventually converges to within 5 mV of zero.

The actual program is given in Figure 20. All addresses used are compatible with the BLC 80/10 microcomputer system. In particular:

- Port A and the ADC0801 are at port address E4
- Port B is at port address E5
- Port C is at port address E6
- PPI control word port is at port address E7
- Program Counter automatically goes to ADDR:3C3D upon acknowledgement of an interrupt from the ADC0801

5.3 Multiple A/D Converters in a Z-80 Interrupt Driven Mode

In data acquisition systems where more than one A/D converter (or other peripheral device) will be interrupting program execution of a microprocessor, there is obviously a need for the CPU to determine which device requires servicing. Figure 21 and the accompanying software is a method of determining which of 7 ADC0801 converters has completed a conversion (\(\text{INTR}\) asserted) and is requesting an interrupt. This circuit allows starting the A/D converters in any sequence, but will input and store valid data from the converters with a priority sequence of A/D 1 being read first, A/D 2 second, etc., through A/D 7 which would have the lowest priority for data being read. Only the converters whose INT is asserted will be read.

The key to decoding circuitry is the DM74LS373, 8-bit D type flip-flop. When the Z-80 acknowledges the interrupt, the program is vectored to a data input Z-80 subroutine. This subroutine will read a peripheral status word from the DM74LS373 which contains the logic state of the \(\text{INTR}\) outputs of all the converters. Each converter which initiates an interrupt will place a logic “0” in a unique bit position in the status word and the subroutine will determine the identity of the converter and execute a data read. An identifier word (which indicates which A/D the data came from) is stored in the next sequential memory location above the location of the data so the program can keep track of the identity of the data entered.

**FIGURE 19. Flow Chart for Auto-Zero Routine**
Figure 20. Software for Auto-Zeroed Differential A/D

5.3 Multiple A/D Converters in a Z-80® Interrupt Driven Mode (Continued)

The following notes apply:

1) It is assumed that the CPU automatically performs a RST 7 instruction when a valid interrupt is acknowledged (CPU is in interrupt mode 1). Hence, the subroutine starting address is 0038H.

2) The address bus from the Z-80 and the data bus to the Z-80 are assumed to be inverted by bus drivers.

3) A/D data and identifying words will be stored in sequential memory locations starting at the arbitrarily chosen address 3E00H.

4) The stack pointer must be dimensioned in the main program as the RST 7 instruction automatically pushes the PC onto the stack and the subroutine uses an additional 6 stack addresses.

5) The peripherals of concern are mapped into I/O space with the following port assignments:

<table>
<thead>
<tr>
<th>HEX PORT ADDRESS</th>
<th>PERIPHERAL</th>
</tr>
</thead>
<tbody>
<tr>
<td>00</td>
<td>MM74C374 8-bit flip-flop</td>
</tr>
<tr>
<td>01</td>
<td>A/D 1</td>
</tr>
<tr>
<td>02</td>
<td>A/D 2</td>
</tr>
<tr>
<td>03</td>
<td>A/D 3</td>
</tr>
<tr>
<td>04</td>
<td>A/D 4</td>
</tr>
<tr>
<td>05</td>
<td>A/D 5</td>
</tr>
<tr>
<td>06</td>
<td>A/D 6</td>
</tr>
<tr>
<td>07</td>
<td>A/D 7</td>
</tr>
</tbody>
</table>

This port address also serves as the A/D identifying word in the program.
## FIGURE 21. Multiple A/Ds with Z-80 Type Microprocessor

### INTERRUPT SERVICING SUBROUTINE

<table>
<thead>
<tr>
<th>LOC</th>
<th>OBJ CODE</th>
<th>STATEMENT</th>
<th>COMMENT</th>
<th>COMMENT</th>
</tr>
</thead>
<tbody>
<tr>
<td>0038</td>
<td>E5</td>
<td>PUSH HL</td>
<td>; Save contents of all registers affected by this subroutine.</td>
<td></td>
</tr>
<tr>
<td>0039</td>
<td>C5</td>
<td>PUSH BC</td>
<td>; this subroutine.</td>
<td></td>
</tr>
<tr>
<td>003A</td>
<td>F5</td>
<td>PUSH AF</td>
<td>; Assumed INT mode set earlier.</td>
<td></td>
</tr>
<tr>
<td>003B</td>
<td>21 00 3E</td>
<td>LD (HL), X3E00</td>
<td>; Initialize memory pointer where data will be stored.</td>
<td></td>
</tr>
<tr>
<td>003E</td>
<td>0E 01</td>
<td>LD C, X01</td>
<td>; C register will be port ADDR for A/D converters.</td>
<td></td>
</tr>
<tr>
<td>0040</td>
<td>D500</td>
<td>OUT X00, A</td>
<td>; Load peripheral status word into 8-bit latch.</td>
<td></td>
</tr>
<tr>
<td>0042</td>
<td>D800</td>
<td>IN A, X00</td>
<td>; Load status word into accumulator.</td>
<td></td>
</tr>
<tr>
<td>0044</td>
<td>47</td>
<td>LD B, A</td>
<td>; Save status word.</td>
<td></td>
</tr>
<tr>
<td>0045</td>
<td>79</td>
<td>TEST LD A, C</td>
<td>; Test to see if the status of all A/D's have been checked. If so, exit subroutine</td>
<td></td>
</tr>
<tr>
<td>0046</td>
<td>FE 08</td>
<td>CP, X08</td>
<td>; Be sure C is set.</td>
<td></td>
</tr>
<tr>
<td>0048</td>
<td>CA 60 00</td>
<td>JPZ, DONE</td>
<td>; If status word is not set, increment C register to point to next A/D, then test next bit in status word.</td>
<td></td>
</tr>
<tr>
<td>004B</td>
<td>7B</td>
<td>LD A, B</td>
<td>; Test a single bit in status word by looking for a &quot;1&quot; to be rotated into the CARRY (an INT)</td>
<td></td>
</tr>
<tr>
<td>004C</td>
<td>1F</td>
<td>RRA</td>
<td>; is loaded as a &quot;1&quot;. If CARRY is set then load</td>
<td></td>
</tr>
<tr>
<td>004D</td>
<td>47</td>
<td>LD B, A</td>
<td>; Contents of A/D at port ADDR in C register.</td>
<td></td>
</tr>
<tr>
<td>004E</td>
<td>DA 5500</td>
<td>JPC, LOAD</td>
<td>; If CARRY is not set, decrement C register to point to next A/D, then test next bit in status word.</td>
<td></td>
</tr>
<tr>
<td>0051</td>
<td>0C</td>
<td>INC C</td>
<td>; Next A/D identifier (A/D port ADDR).</td>
<td></td>
</tr>
<tr>
<td>0055</td>
<td>ED 78</td>
<td>LOAD IN A, (C)</td>
<td>; Read data from interrupting A/D and invert</td>
<td></td>
</tr>
<tr>
<td>0057</td>
<td>EE FF</td>
<td>XOR FF</td>
<td>; the data.</td>
<td></td>
</tr>
<tr>
<td>0059</td>
<td>77</td>
<td>LD (HL), A</td>
<td>; Store the data</td>
<td></td>
</tr>
<tr>
<td>005A</td>
<td>2C</td>
<td>INC L</td>
<td>; Store A/D identifier (A/D port ADDR).</td>
<td></td>
</tr>
<tr>
<td>005B</td>
<td>71</td>
<td>LD (HL), C</td>
<td>; Store A/D identifier (A/D port ADDR).</td>
<td></td>
</tr>
<tr>
<td>005C</td>
<td>2C</td>
<td>INC L</td>
<td>; Return to original program</td>
<td></td>
</tr>
<tr>
<td>005D</td>
<td>C3 51 00</td>
<td>JP, NEXT</td>
<td>; Test next bit in status word.</td>
<td></td>
</tr>
<tr>
<td>0060</td>
<td>F1</td>
<td>DONE POP AF</td>
<td>; Re-establish all registers as they were</td>
<td></td>
</tr>
<tr>
<td>0061</td>
<td>C1</td>
<td>POP BC</td>
<td>; before the interrupt.</td>
<td></td>
</tr>
<tr>
<td>0062</td>
<td>E1</td>
<td>POP HL</td>
<td>; Return to original program</td>
<td></td>
</tr>
<tr>
<td>0063</td>
<td>C9</td>
<td>RET</td>
<td>; Return to original program</td>
<td></td>
</tr>
</tbody>
</table>
### Ordering Information

<table>
<thead>
<tr>
<th>TEMP RANGE</th>
<th>0°C TO 70°C</th>
<th>0°C TO 70°C</th>
<th>0°C TO 70°C</th>
<th>−40°C TO +85°C</th>
</tr>
</thead>
<tbody>
<tr>
<td>ERROR</td>
<td></td>
<td></td>
<td></td>
<td>ADC0801LCN</td>
</tr>
<tr>
<td>±1/4 Bit</td>
<td>ADC0802LCWM</td>
<td>ADC0802LCW</td>
<td>ADC0802LCV</td>
<td>ADC0802LCN</td>
</tr>
<tr>
<td>Adjusted</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>±1/2 Bit</td>
<td>ADC0803LCWM</td>
<td>ADC0803LCV</td>
<td>ADC0803LCN</td>
<td></td>
</tr>
<tr>
<td>Unadjusted</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>±1 Bit</td>
<td>ADC0804LCWM</td>
<td>ADC0804LCV</td>
<td>ADC0804LCN</td>
<td>ADC0805LCN</td>
</tr>
<tr>
<td>Unadjusted</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

| PACKAGE OUTLINE | M20B—Small Outline | V20A—Chip Carrier | N20A—Molded DIP |

### Temp Range

<table>
<thead>
<tr>
<th>TEMP RANGE</th>
<th>−40°C TO +85°C</th>
<th>−55°C TO +125°C</th>
</tr>
</thead>
<tbody>
<tr>
<td>ERROR</td>
<td></td>
<td>ADC0801LJ</td>
</tr>
<tr>
<td>±1/4 Bit</td>
<td>ADC0801LCJ</td>
<td>ADC0802LJ,</td>
</tr>
<tr>
<td>Adjusted</td>
<td></td>
<td>ADC0802LJ/883</td>
</tr>
<tr>
<td>±1/2 Bit</td>
<td>ADC0802LCJ</td>
<td>ADC0803LCJ</td>
</tr>
<tr>
<td>Unadjusted</td>
<td>ADC0803LCJ</td>
<td>ADC0804LCJ</td>
</tr>
<tr>
<td>±1 Bit</td>
<td>ADC0804LCJ</td>
<td></td>
</tr>
<tr>
<td>Unadjusted</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

| PACKAGE OUTLINE | J20A—Cavity DIP | J20A—Cavity DIP |

### Connection Diagrams

#### ADC080X
Dual-In-Line and Small Outline (SO) Packages

- CS: 1
- RD: 2
- WR: 3
- CLK IN: 4
- INTR: 5
- V IN(+): 6
- V IN(-): 7
- A GND: 8
- V REF/2: 9
- D GND: 10
- V CC (OR V REF): 20

#### ADC080X
Molded Chip Carrier (PCC) Package

- CS: 1
- RD: 2
- WR: 3
- CLK IN: 4
- INTR: 5
- V IN(+): 6
- V IN(-): 7
- A GND: 8
- V REF/2: 9
- V CC (OR V REF): 20

#### Connection Diagrams

See Ordering Information
Molded Dual-In-Line Package (N)
Order Number ADC0801LCN, ADC0802LCN, ADC0803LCN, ADC0804LCN or ADC0805LCN
NS Package Number N20A
LIFE SUPPORT POLICY

NATIONAL'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF NATIONAL SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform, when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.

2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

National does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and National reserves the right at any time without notice to change said circuitry and specifications.